HAT2045T

Silicon N Channel Power MOS FET High Speed Power Switching

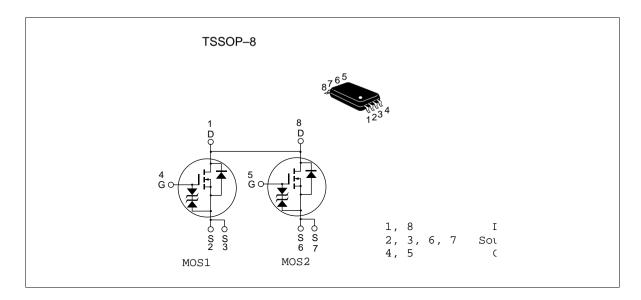
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Target Specification 5th. Edition February 1999

Features

- Low on-resistance
- Capable of 2.5 V gate drive
- Low drive current
- High density mounting

Outline





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Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{ exttt{DSS}}$	28	V
Gate to source voltage	$V_{\rm GSS}$	±12	V
Drain current	I _D	6.0	A
Drain peak current	Note1 D(pulse)	48	A
Body-drain diode reverse drain current	I _{DR}	6.0	A
Channel dissipation	Pch Note2	1.0	W
Channel dissipation	Pch Note3	1.5	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. PW \leq 10 μ s, duty cycle \leq 1 %

- 2. 1 Drive operation; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10s
- 3. 2 Drive operation; When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW \leq 10s

Electrical Characteristics ($Ta = 25^{\circ}C$)

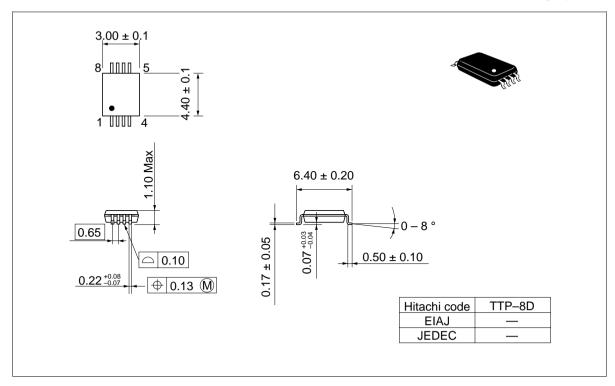
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	28	_	_	V	$I_D = 10$ mA, $V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±12	_	_	V	$I_{G} = \pm 100 \mu A, \ V_{DS} = 0$
Gate to source leak current	$I_{\rm GSS}$	_	_	±10	μΑ	$V_{GS} = \pm 10V, \ V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 28 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	0.4	_	1.4	V	$V_{DS} = 10V$, $I_D = 1mA$
Static drain to source on state	$R_{\text{DS(on)}}$	_	0.020	0.025	Ω	$I_D = 3A$, $V_{GS} = 4V^{Note4}$
resistance	$R_{\text{DS(on)}}$	_	0.027	0.037	Ω	$I_D = 3A, V_{GS} = 2.5V^{Note4}$
Forward transfer admittance	y _{fs}	8	13	_	S	$I_{\rm D} = 3A, V_{\rm DS} = 10V^{\rm Note4}$
Input capacitance	Ciss	_	680	_	pF	V _{DS} = 10V
Output capacitance	Coss	_	240	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	170	_	pF	f = 1MHz
Turn-on delay time	$t_{\text{d(on)}}$	_	12	_	ns	$V_{GS} = 4V$, $I_D = 3A$
Rise time	t _r	_	110	_	ns	$V_{DD} \cong 10V$
Turn-off delay time	$t_{\text{d(off)}}$	_	90	_	ns	
Fall time	t _f	_	100	_	ns	
Body-drain diode forward voltage	V_{DF}	_	0.85	1.1	V	IF =6.0A, $V_{GS} = 0^{Note4}$
Body-drain diode reverse recovery time	t _{rr}	_	40	_	ns	IF = 6.0A, $V_{GS} = 0$ diF/ dt =20A/ μ s

Note: 4. Pulse test

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Package Dimensions

Unit: mm



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Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead

Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218

Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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